

Title (en)

PRINTABLE ETCHING MEDIA FOR SILICON DIOXIDE AND SILICON NITRIDE LAYERS

Title (de)

DRUCKFÄHIGE ÄTZMEDIEN FÜR SILIZIUMDIOXID- UND SILIZIUMNITRIDSCHICHTEN

Title (fr)

AGENTS D'ATTAQUE ADAPTES A L'IMPRESSION, DESTINES A DES COUCHES DE DIOXYDE DE SILICIUM ET DE NITRURE DE SILICIUM

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2007009546A1] The present invention relates to a novel printable etching medium having non-Newtonian flow behaviour for etching surfaces in the production of solar cells, and also to the use thereof. The present invention furthermore also relates to etching and doping media which are suitable both for etching inorganic layers and for doping underlying layers. In particular, corresponding particle-containing compositions are involved which can be used to etch extremely fine structures very selectively without damaging or attacking adjoining areas.

IPC 8 full level

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